

XBS303V19R-G

ETR16022-002

Schottky Barrier Diode, 3A, 30V Type

FEATURES

Forward Voltage	: $V_F=0.355V$ (TYP.)
Forward Current	: $I_{F(AVE)}=3A$
Repetitive Peak Reverse Voltage	: $V_{RM}=30V$

ABSOLUTE MAXIMUM RATINGS

Ta=25°C

PARAMETER	SYMBOL	RATINGS	UNITS
Repetitive Peak Reverse Voltage	V_{RM}	30	V
Reverse Voltage	V_R	30	V
Forward Current (Average)	$I_{F(AVE)}$	3	A
Non Continuous Forward Surge Current ^{*1}	I_{FSM}	60	A
Junction Temperature	T_J	125	°C
Storage Temperature Range	T_{stg}	-55~+150	°C

*1 : Non continuous high amplitude 60Hz half-sine wave.

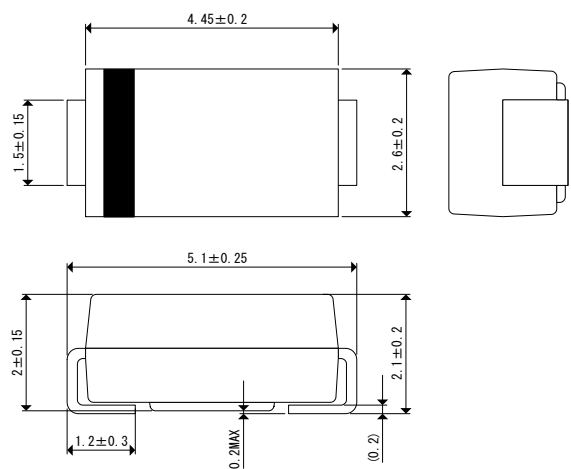
APPLICATIONS

- Rectification
- Protection against reverse connection of battery

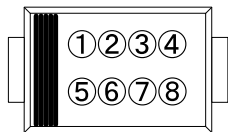
PACKAGING INFORMATION

SMA-XG

Unit: mm



MARKING RULE



①②③④⑤⑥: 303V19(Product Number)
⑦⑧ : Assembly Lot Number

PRODUCT NAME

PRODUCT NAME	PACKAGE	ORDER UNIT
XBS303V19R-G ^(*)	SMA-XG	2,000/Reel

(*) The "-G" suffix denotes Halogen and Antimony free as well as being fully RoHS compliant.

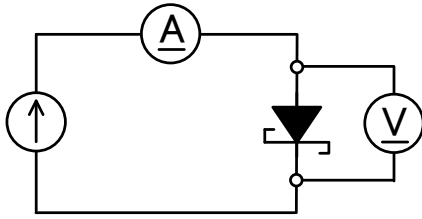
ELECTRICAL CHARACTERISTICS

Ta=25°C

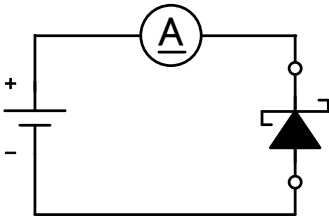
PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS	CIRCUIT
Forward Voltage	V_{F1}	$I_F=0.5A$	-	0.265	0.34	V	①
	V_{F2}	$I_F=1A$	-	0.295	0.36	V	①
	V_{F3}	$I_F=3A$	-	0.355	0.39	V	①
Reverse Current	I_R	$V_R=30V$	-	0.35	3	mA	②
Inter-Terminal Capacity	C_t	$V_R=1V$, $f=1MHz$	-	385	-	pF	③
Reverse Recovery Time	t_{rr}	$I_F=I_R=10mA$, $i_{rr}=1mA$	-	90	-	ns	④

■ TEST CIRCUITS

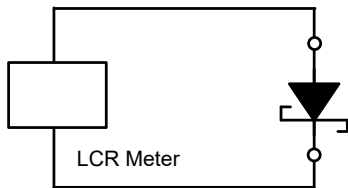
< Circuit ① >



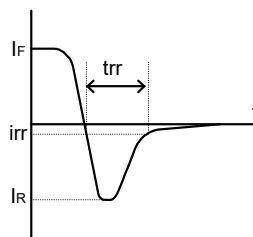
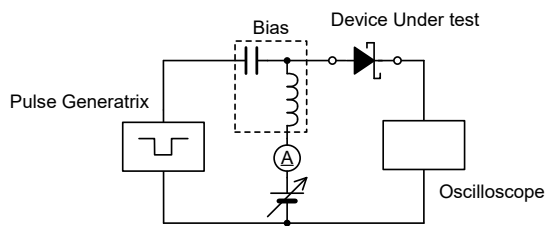
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< Circuit ③ >



< Circuit ④ >

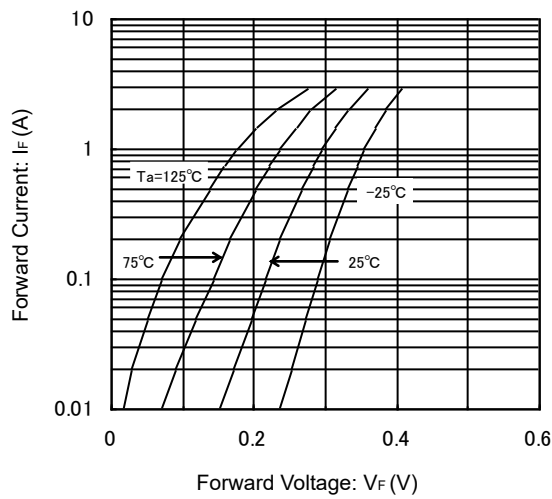


■ NOTES ON USE

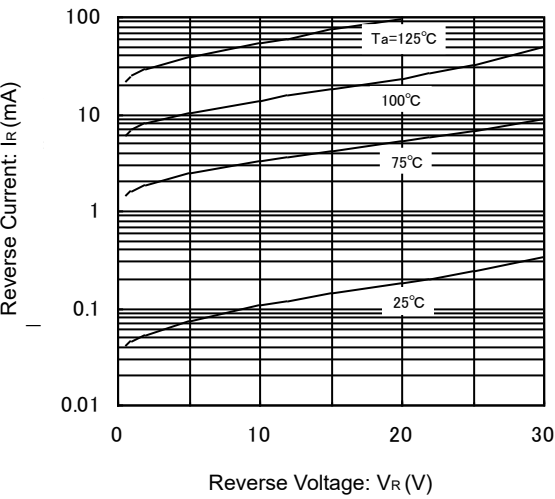
- 1) Please use this IC within the absolute maximum ratings.
- 2) Even within the ratings, in case of high load use continuously such as high temperature, high voltage, high current and thermal stress may cause reliability degradation of the IC. Adequate "Derating" should be taken into consideration while designing.
- 3) Torex places an importance on improving our products and their reliability. We request that users incorporate fail-safe designs and post-aging protection treatment when using Torex products in their systems.

■ TYPICAL PERFORMANCE CHARACTERISTICS

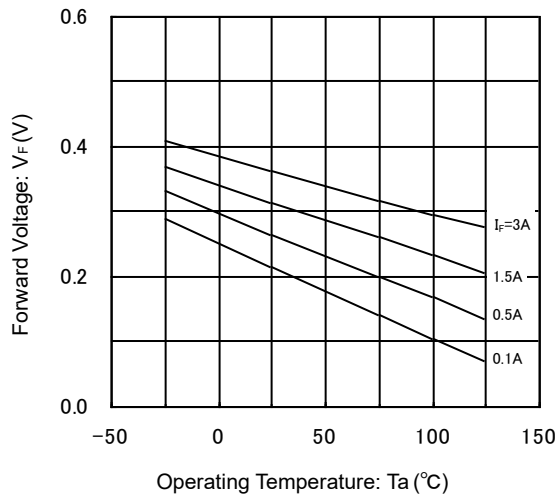
(1) Forward Current vs. Forward Voltage



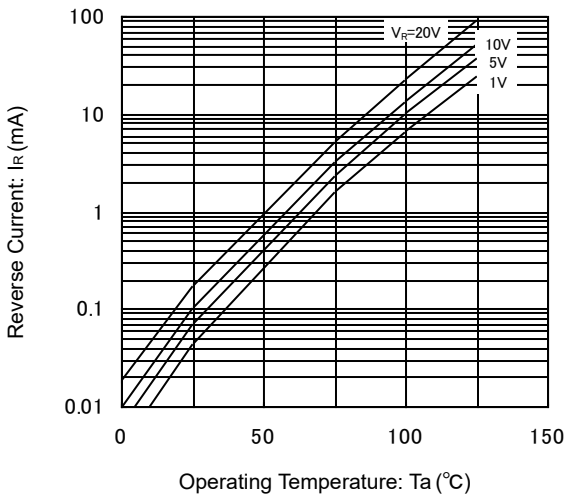
(2) Reverse Current vs. Reverse Voltage



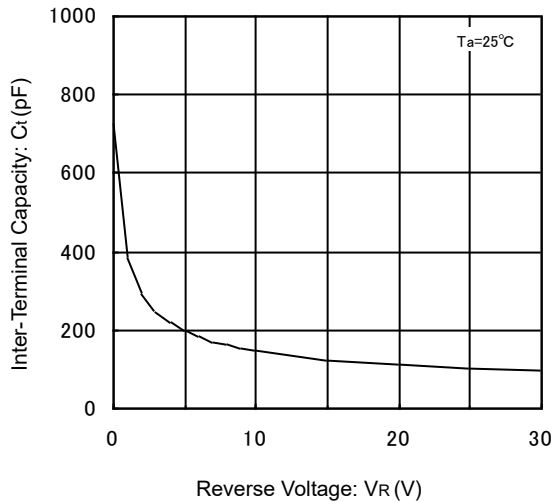
(3) Forward Voltage vs. Operating Temperature



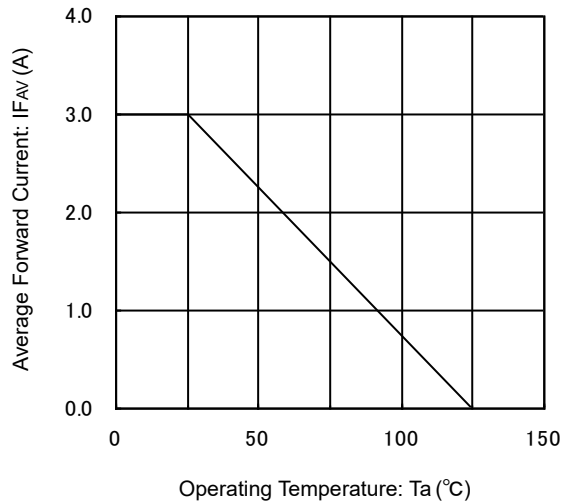
(4) Reverse Current vs. Operating Temperature



(5) Inter-Terminal Capacity vs. Reverse Voltage



(6) Average Forward Current vs. Operating Temperature



XBS303V19R-G

■PACKAGING INFORMATION

For the latest package information go to, www.torexsemi.com/technical-support/packages

PACKAGE	OUTLINE / LAND PATTERN	THERMAL CHARACTERISTICS
SMA-XG	SMA-XG PKG	

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